**Product data sheet** 

## 1. General description

Dual common cathode power Schottky diode designed for high frequency switched mode power supplies in a TO220F "full pack" plastic package.





## 2. Features and benefits

- Trench structure
- High junction temperature up to 150 °C
- · Low forward voltage drop, negligible switching losses
- High efficiency

## 3. Applications

- · DC to DC converters
- · Freewheeling diode
- OR-ing diode

## 4. Quick reference data

### Table 1. Quick reference data

Symbol	Parameter	Conditions	Values			Unit	
Absolute	Absolute maximum rating						
$V_{RRM}$	repetitive peak reverse voltage		100			V	
$I_{F(AV)}$	average forward current	$\delta$ = 0.5; square-wave pulse; per diode; Fig. 1; Fig. 2; Fig. 3	10 A		А		
I <sub>O(AV)</sub>	average output current	$\delta$ = 0.5 ; square-wave pulse; both diodes conducting	20		А		
Symbol	Parameter	Conditions	Min Typ Max		Unit		
Static ch	aracteristics						
$V_{F}$	forward voltage	$I_F = 5 \text{ A}; T_j = 25 \text{ °C}; \text{ per diode}; Fig. 6$		-	0.54	0.62	V
		I <sub>F</sub> = 5 A; T <sub>j</sub> = 125 °C; per diode; <u>Fig. 6</u>		-	0.51	0.58	V
		I <sub>F</sub> = 10 A; T <sub>j</sub> = 25 °C; per diode; <u>Fig. 6</u>		-	0.68	0.75	V
		I <sub>F</sub> = 10 A; T <sub>j</sub> = 125 °C; per diode; <u>Fig. 6</u>		-	0.63	0.7	V
I <sub>R</sub>	reverse current	$V_R = 100 \text{ V}$ ; $T_j = 25 \text{ °C}$ ; per diode; Fig. 7; Fig. 8		-	-	50	μA
		$V_R = 100 \text{ V}; T_j = 125 \text{ °C}; \text{ per diode}; $ Fig. 7; Fig. 8		-	-	15	mA

# 5. Pinning information

### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A1	anode 1	mb	
2	K	cathode		A1 A2
3	A2	anode 2		K sym125
mb	n.c.	mounting base; isolated		ojEv

# 6. Ordering information

### **Table 3. Ordering information**

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WN3S20H100CX	TO220F	WN3S20H100CXQ	Tube	50	SOT186A	14-Nov-2013

## 7. Marking

## Table 4. Marking codes

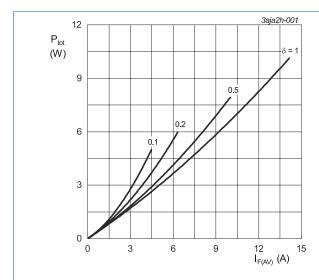
Type number	Marking codes
WN3S20H100CX	WN3S 20H100CX

## 8. Limiting values

### **Table 5. Limiting values**

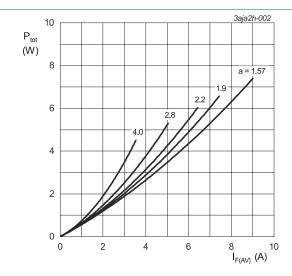
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage		100	V
$V_{\text{RWM}}$	crest working reverse voltage		100	V
$V_R$	reverse voltage	DC	100	V
$I_{F(AV)}$	average forward current	$\delta$ = 0.5 ; square-wave pulse; per diode; Fig. 1; Fig. 2; Fig. 3	10	А
$I_{O(AV)}$	average output current	$\delta$ = 0.5 ; square-wave pulse; both diodes conducting	20	А
I <sub>FSM</sub>	non-repetitive peak forward current	$t_p$ = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; per diode; Fig. 4	180	А
		$t_p$ = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; per diode	198	А
T <sub>stg</sub>	storage temperature		-40 to 150	°C
T <sub>j</sub>	junction temperature		150	°C



$$\begin{split} I_{F(AV)} &= I_{F(RMS)} \times \sqrt{\delta} \\ V_o &= 0.531 \text{ V; } R_s = 0.0131 \text{ } \Omega \end{split}$$

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values; per diode



a = form factor =  $I_{F(RMS)}$  /  $I_{F(AV)}$ V<sub>o</sub> = 0.531 V; R<sub>s</sub> = 0.0131  $\Omega$ 

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values; per diode

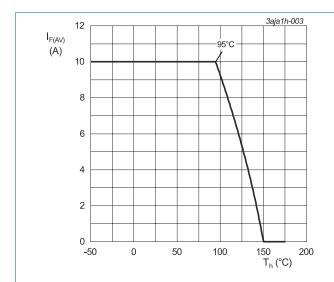


Fig. 3. Average forward current as a function of heatsink temperature; maximum values; per diode

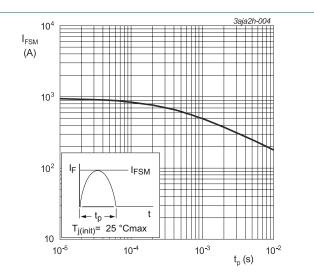


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values; per diode

## 9. Thermal characteristics

#### **Table 6. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R <sub>th(j-h)</sub> thermal resistance from junction to		with heatsink compound; per diode; Fig. 5	-	-	7	K/W
heatsink	heatsink	with heatsink compound; both diodes conducting	-	-	4.8	K/W
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient free air	in free air	-	65	-	K/W

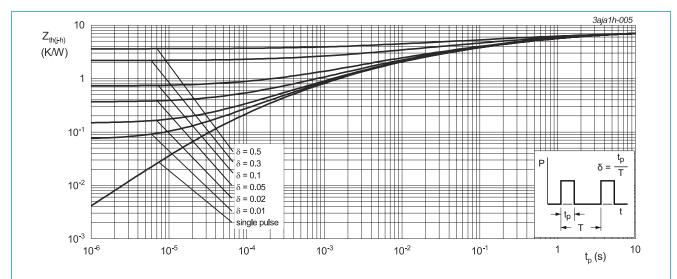


Fig. 5. Transient thermal impedance from junction to heatsink as a function of pulse duration; maximum values; per diode

## 10. Isolation characteristics

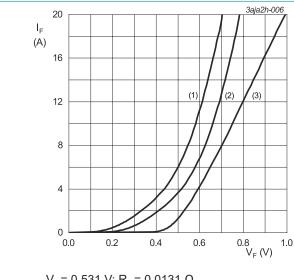
### **Table 7. Isolation characteristics**

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V <sub>isol(RMS)</sub>	RMS isolation voltage	from all terminals to external heatsink; sinusoidal waveform; clean and dust free; 50 Hz $\leq$ f $\leq$ 60 Hz; T <sub>h</sub> = 25 °C; RH $\leq$ 65 %	-	-	2500	V

## 11. Characteristics

**Table 8. Characteristics** 

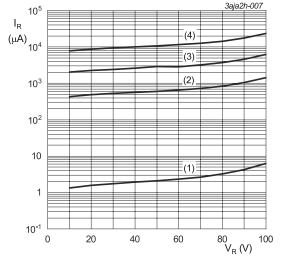
Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Static characteristics							
V <sub>F</sub>	forward voltage	$I_F = 5 \text{ A}$ ; $T_j = 25 \text{ °C}$ ; per diode; Fig. 6		-	0.54	0.62	V
		I <sub>F</sub> = 5 A; T <sub>j</sub> = 125 °C; per diode; <u>Fig. 6</u>		-	0.51	0.58	V
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		I <sub>F</sub> = 10 A; T <sub>j</sub> = 125 °C; per diode; <u>Fig. 6</u>		-	0.63	0.7	V
I <sub>R</sub>	reverse current	$V_R = 100 \text{ V}; T_j = 25 \text{ °C}; \text{ per diode}; $ Fig. 7; Fig. 8		-	-	50	μΑ
		$V_R = 100 \text{ V}; T_j = 125 ^{\circ}\text{C}; \text{ per diode}; $ Fig. 7; Fig. 8		-	-	15	mA





<sup>(1)</sup> T<sub>i</sub> = 150 °C; typical values

Fig. 6. Forward current as a function of forward voltage; per diode



(1) T<sub>i</sub> = 25 °C; typical values

Fig. 7. Reverse leakage current as a function of reverse voltage; per diode; typical values

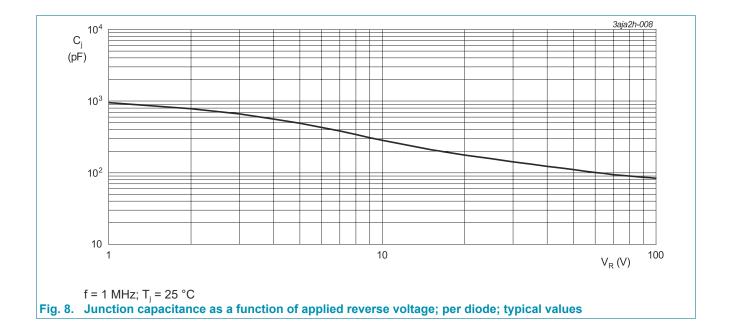
<sup>(2)</sup> T<sub>i</sub> = 150 °C; maximum values

<sup>(3)</sup>  $T_i = 25$  °C; maximum values

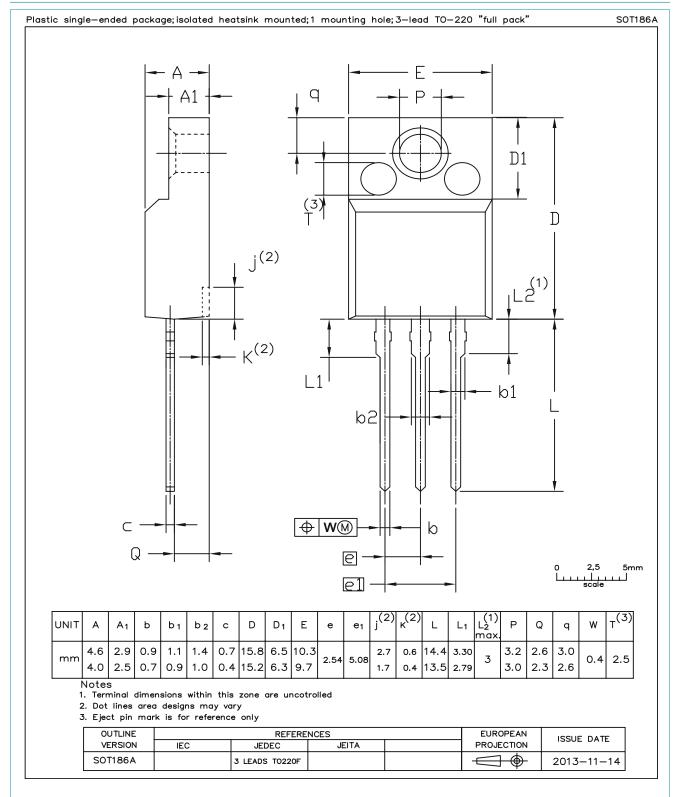
<sup>(2)</sup> T<sub>i</sub> = 100 °C; typical values

<sup>(3)</sup>  $T_j = 125$  °C; typical values

<sup>(4)</sup> T<sub>i</sub> = 150 °C; typical values



## 12. Package outline



## 13. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

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## 14. Contents

1. General description	1
2. Features and benefits	1
3. Applications	1
4. Quick reference data	1
5. Pinning information	2
6. Ordering information	2
7. Marking	2
8. Limiting values	3
9. Thermal characteristics	5
10. Isolation characteristics	5
11. Characteristics	6
12. Package outline	8
13. Legal information	9
14. Contents	

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